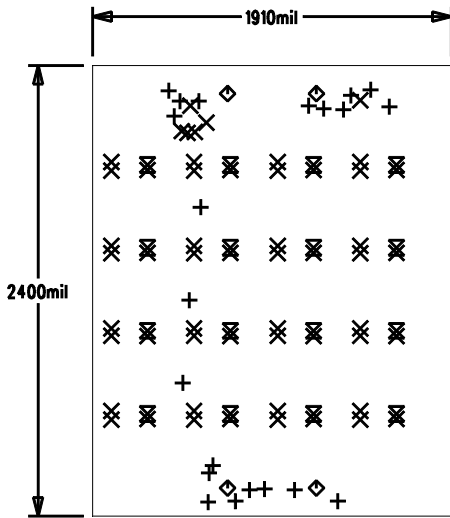


LAYER NAME	4	ASSEMBLY TO BE CONSIDERED
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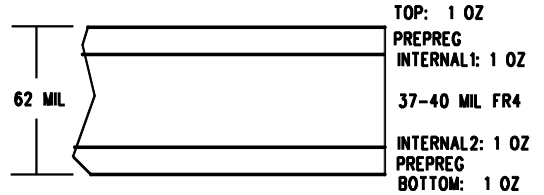
SIZE	QTY	SYM	PLATED	TOL
13	21	+	YES	+/-0.0
10	54	×	YES	+/-0.0
47.24	4	◇	NO	+/-0.0
22	16	⊗	NO	+/-0.0

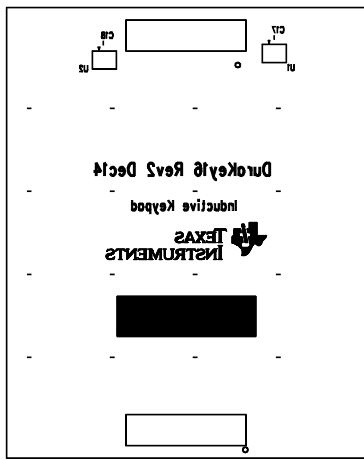


LAYER NAME	1	TDRILCORROWING
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Overall Board Thickness: 62 Mil
 Soldermask Color: Red
 Silkscreen Color: White
 Drill hole tolerance: +/-3 Mil
 Copper/Spacing Clearances: 5/5 Mil

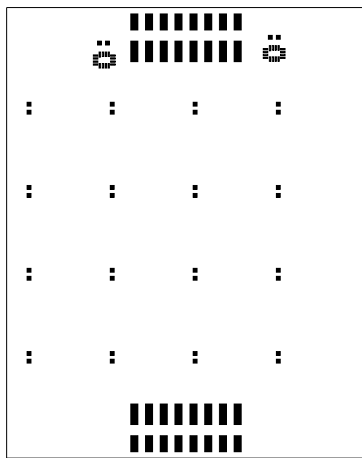
COMPANY	TI-SVA		
PCB PART NUMBER	DK16	REV	2
DATE	12/10/14		
NOTES			



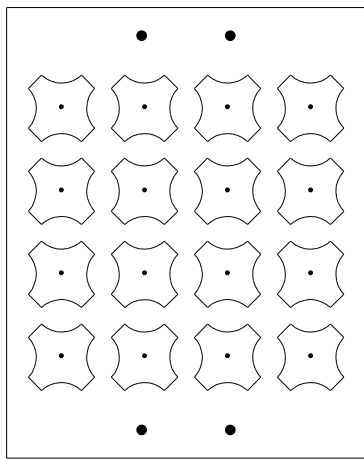


LAYER NAME

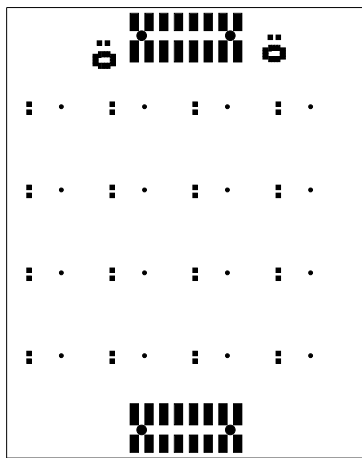
SILKSCREEN BOTTOM



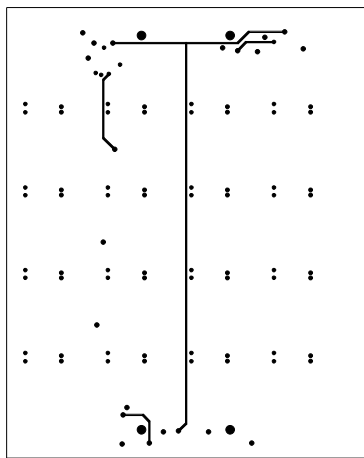
LAYER NAME		PASTE MASK BOTTOM
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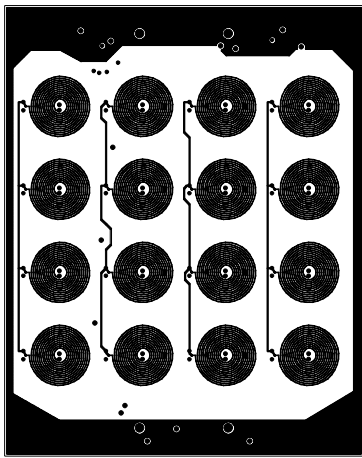
LAYER NAME	SOLDER MASK TOP
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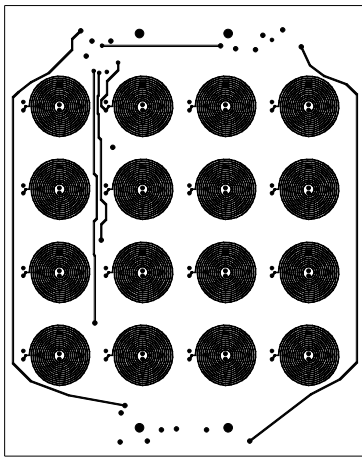
LAYER NAME	SOLDER MASK BOTTOM
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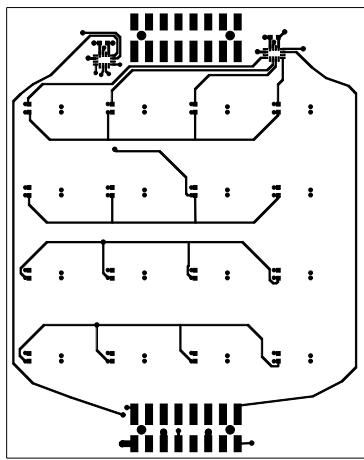
LAYER NAME	1	TOP COMPONENT
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LAYER NAME	2	GROUND PLANE
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LAYER NAME	3	POWER POUR
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LAYER NAME	4	BOTTOM COMPONENT
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